

**isc P-Channel MOSFET Transistor**

**IRF5305, IIRF5305**

**• FEATURES**

- Static drain-source on-resistance:  
 $R_{ds(on)} \leq 0.06\Omega$
- Enhancement mode:
- 100% avalanche tested
- Minimum Lot-to-Lot variations for robust device performance and reliable operation

**• DESCRIPTION**

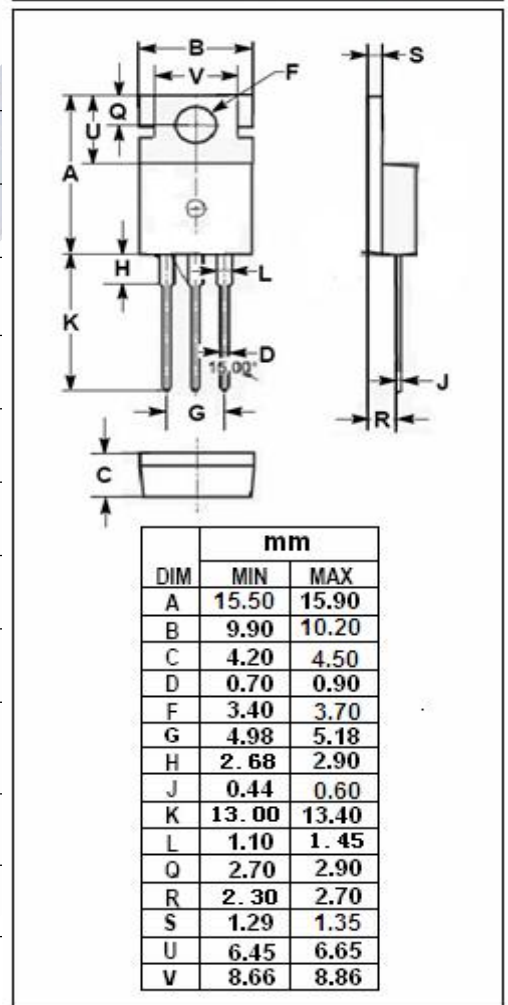
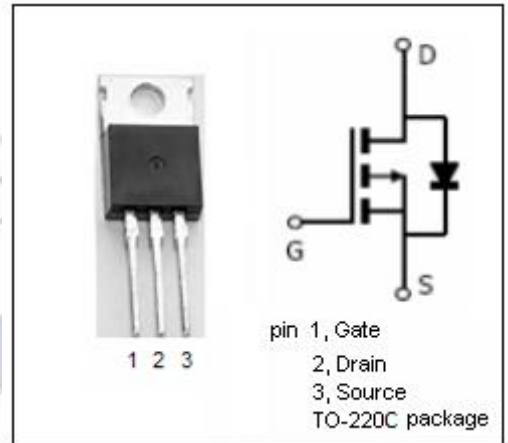
- Combine with the fast switching speed and ruggedized device design, provide the designer with an extremely efficient and reliable device for use in a wide variety of applications.

**• ABSOLUTE MAXIMUM RATINGS ( $T_a=25^\circ\text{C}$ )**

| SYMBOL    | PARAMETER                                  | VALUE    | UNIT             |
|-----------|--|----------|------------------|
| $V_{DS}$  | Drain-Source Voltage                       | -55      | V                |
| $V_{GS}$  | Gate-Source Voltage                        | $\pm 20$ | V                |
| $I_D$     | Drain Current-Continuous                   | -31      | A                |
| $I_{DM}$  | Drain Current-Single Pulsed                | -110     | A                |
| $P_D$     | Total Dissipation @ $T_c=25^\circ\text{C}$ | 110      | W                |
| $T_j$     | Max. Operating Junction Temperature        | 175      | $^\circ\text{C}$ |
| $T_{stg}$ | Storage Temperature                        | -55~175  | $^\circ\text{C}$ |

**• THERMAL CHARACTERISTICS**

| SYMBOL        | PARAMETER                             | MAX | UNIT               |
|---------------|---------------------------------------|-----|--------------------|
| $R_{th(j-c)}$ | Channel-to-case thermal resistance    | 1.4 | $^\circ\text{C/W}$ |
| $R_{th(j-a)}$ | Channel-to-ambient thermal resistance | 62  | $^\circ\text{C/W}$ |



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**ELECTRICAL CHARACTERISTICS**

 T<sub>C</sub>=25°C unless otherwise specified

| SYMBOL              | PARAMETER                      | CONDITIONS   | MIN  | TYP | MAX  | UNIT |
|---------------------|--------------------------------|--|------|-----|------|------|
| BV <sub>DSS</sub>   | Drain-Source Breakdown Voltage | V <sub>GS</sub> =0V; I <sub>D</sub> = -250 μ A               | -55  |     |      | V    |
| V <sub>GS(th)</sub> | Gate Threshold Voltage         | V <sub>DS</sub> =V <sub>GS</sub> ; I <sub>D</sub> = -250 μ A | -2.0 |     | -4.0 | V    |
| R <sub>DS(on)</sub> | Drain-Source On-Resistance     | V <sub>GS</sub> = -10V; I <sub>D</sub> = -16A                |      |     | 0.06 | Ω    |
| I <sub>GSS</sub>    | Gate-Source Leakage Current    | V <sub>GS</sub> = ±20V                                       |      |     | ±100 | nA   |
| I <sub>DSS</sub>    | Drain-Source Leakage Current   | V <sub>DS</sub> = -55V; V <sub>GS</sub> = 0V                 |      |     | -25  | μ A  |
| V <sub>SD</sub>     | Diode forward voltage          | I <sub>S</sub> = -16A; V <sub>GS</sub> = 0V                  |      |     | -1.3 | V    |